

Dual N-Channel MOSFET

General Description

The WSD6042DN33 is the highest performance trench Dual N-Channel MOSFET with extreme high cell density, which provide excellent $R_{DS(ON)}$ and gate charge for most of the synchronous buck converter applications.

The WSD6042DN33 meet the RoHS and Green Product requirement 100% E_{AS} guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% E_{AS} Guaranteed
- Green Device Available

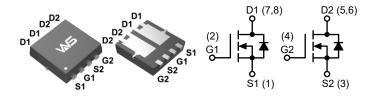
Product Summery

BV _{DSS}	R _{DS(ON)}	Ι _D
60V	14mΩ	45A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFN3X3-8L Pin Configuration



Symbol Units **Parameter** Rating **Drain-Source Voltage** 60 V_{DS} V Gate-Source Voltage ±20 V_{GS} I_D@T_C=25°C Continuous Drain Current, V_{GS} @ 10V¹ 45 I_D@T_C=100°C Continuous Drain Current, V_{GS} @ 10V¹ 22 А Pulsed Drain Current² 150 I_{DM} Single Pulse Avalanche Energy³ E_{AS} 50 mJ Avalanche Current I_{AS} 14 Α $P_D@T_C=25^{\circ}C$ 36 Power Dissipation ⁴ W P_D@T_A=25°C Power Dissipation ⁴ 2.5 Storage Temperature Range -55 to 150 T_{STG} °C -55 to 150 $T_{\rm J}$ **Operating Junction Temperature Range**

Thermal Data

Symbol	Parameter	Тур.	Max.	Units		
R _{θJA}	Thermal Resistance, Junction-to-Ambient ¹		80	°C/M		
R _{θJC}	Thermal Resistance, Junction-to-Case ¹		3.6	°C/W		

Absolute Maximum Ratings



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Electrical Characteristics (T_J=25°C, Unless Otherwise Noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage V _{GS} =0V,I _D =250µA		60			V
$\Delta BV_{DSS}/\Delta T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =1mA		0.063		V/°C
B	Statia Drain Sauras On Desistance 2	V _{GS} =10V , I _D =15A		14	15	mΩ
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =10A		17	19	11122
V _{GS(th)}	Gate Threshold Voltage		1.0	1.7	2.5	V
$\Delta V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	- V _{GS} =V _{DS} ,I _D =250μA		-5.08		mV/°C
_	Drain Source Lookage Current	V_{DS} =48V , V_{GS} =0V , T_J =25°C			1.0	
I _{DSS}	Drain-Source Leakage Current	V_{DS} =48V , V_{GS} =0V , T_J =55°C			5.0	μA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V, V_{DS} =0V			±100	nA
9 _{fs}	Forward Transconductance	V _{DS} =5V , I _D =15A		35		S
R _g	Gate Resistance V _{DS} =0V , V _{GS} =0V , f = 1.0MHz			3.2		Ω
Qg	Total Gate Charge (4.5V)			12.6		
Q _{gs}	Gate-Source Charge	V_{DS} =30V , V_{GS} =4.5V , I_{D} =12A		2.2		nC
Q _{gd}	Gate-Drain Charge			1.3		
T _{d(on)}	Turn-On Delay Time			3.5		
T _r	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$			11		
T _{d(off)}				10		ns
T _f	Fall Time]		5.6		
C _{iss}	Input Capacitance	ice		710		
C _{oss}	Output Capacitance V_{DS} =15V , V_{GS} =0V , f = 1.0MHz			220		pF
C _{rss}	Reverse Transfer Capacitance]		14		

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
E _{AS}	Single Pulse Avalanche Energy ⁵	V _{DD} =25V,L=0.5mH,I _{AS} =22A	50			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
۱ _S	Continuous Source Current ^{1,6}	V =V =0V Force Current			45	A
I _{SM}	Pulsed Source Curren ^{2,6}	V _G =V _D =0V,Force Current			90	А
V _{SD}	Diode Forward Voltage 2 V _{GS} =0V , I _S =1A , T _J =25°C				1.2	V
t _{rr}	Reverse Recovery Time			22		ns
Q _{rr}	Reverse Recovery Charge	l _F =15A, dl/dt=100A/µs,T _J =25°C		51		nC

Note:

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t≤10sec.

2. The data tested by pulsed , pulse width \leq 300µs , duty cycle \leq 2%

3. The E_{AS} data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.5mH, I_{AS}=22A

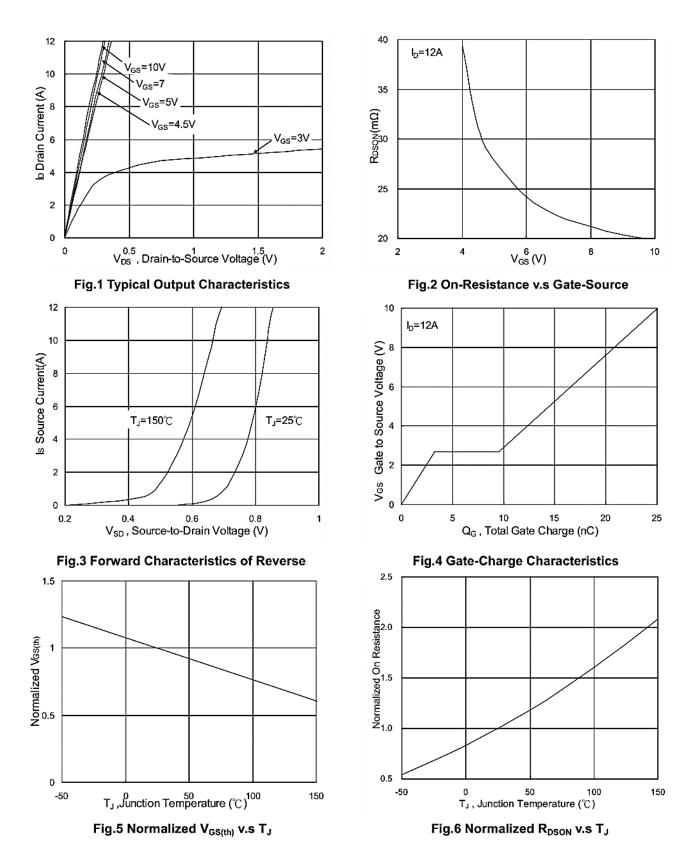
- 4. The power dissipation is limited by 150 $^{\circ}\text{C}$ junction temperature.
- 5. The Min. value is 100% $\,E_{AS}\,$ tested guarantee.

6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



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Typical Characteristics





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Typical Characteristics (Cont.)

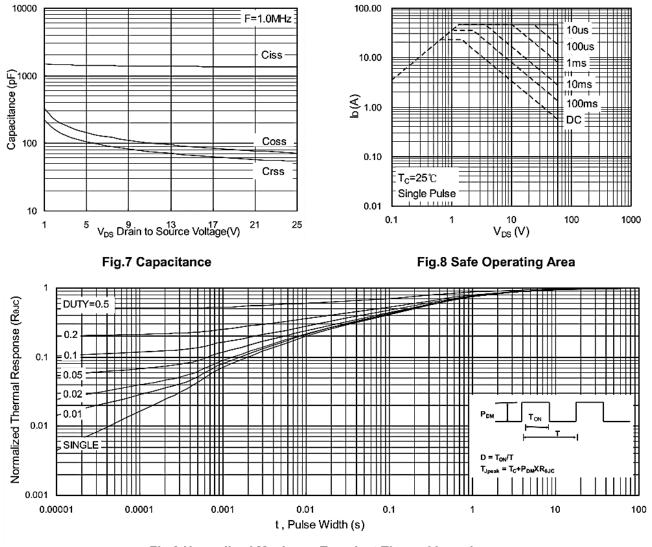
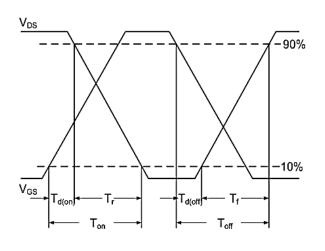


Fig.9 Normalized Maximum Transient Thermal Impedance





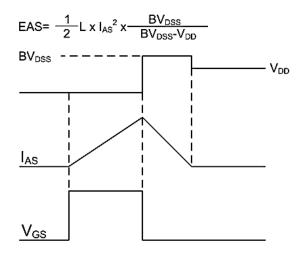
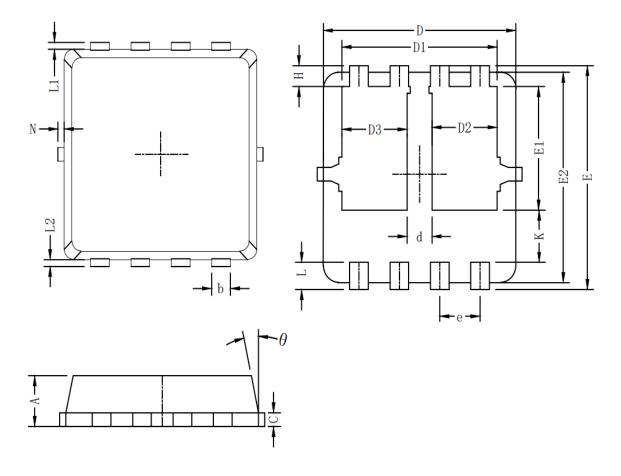


Fig.11 Unclamped Inductive Waveform



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Packaging information



Symbol -	Dim in mm				
	min	typ	max		
А	0.6	0.75	0.9		
b	0.2	0.3	0.4		
С	0.15	0.2	0.25		
D	3	3.1	3.2		
D1	2.3	2.45	2.6		
D2/D3	0.8	1	1.2		
E	3.15	3.3	3.45		
E1	1.43	1.73	1.93		
E2	2.9	3.05	3.2		
е		0.65BSC			
Н	0.2	0.35	0.5		
К	0.57	0.77	0.87		
L	0.3	0.4	0.5		
L1/L2	0.1REF				
θ	8°	10°	13°		
Ν	0		0.15		
d	0.3	0.4	0.5		



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